

XRT75L02

TWO CHANNEL E3/DS3/STS-1 LINE INTERFACE UNIT WITH JITTER

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GENERAL DESCRIPTION

The XRT75L02 is a two-channel fully integrated Line Interface Unit (LIU) with Jitter Attenuator for E3/DS3/STS-1 applications. It incorporates independent Receivers, Transmitters and Jitter Attenuators in a single 100 pin TQFP package.

The XRT75L02 can be configured to operate in either E3 (34.368 MHz), DS3 (44.736 MHz) or STS-1 (51.84 MHz) modes. The transmitter can be turned off (tristated) for redundancy support and for conserving power.

The XRT75L02's differential receiver provides high noise interference margin and is able to receive the data over 1000 feet of cable or with up to 12 dB of cable attenuation.

The XRT75L02 incorporates advanced crystal-less jitter attenuators that can be selected either in the transmit or receive path. The jitter attenuator performance meets the ETSI TBR-24 and Bellcore GR-499 specifications.

The XRT75L02 provides both Serial Microprocessor Interface as well as Hardware mode for programming and control.

The XRT75L02 supports local,remote and digital loop-backs. The XRT75L02 also contains an on-board Pseudo Random Binary Sequence (PRBS) generator and detector with the ability to insert and detect single bit error.

FEATURES

RECEIVER:

- On chip Clock and Data Recovery circuit for high input jitter tolerance.
- Meets the jitter tolerance requirements as specified in ITU-T G.823_1993 for E3 and Telcordia GR-499-CORE for DS3 applications.
- Detects and Clears LOS as per G.775.
- Receiver Monitor mode handles up to 20 dB flat loss with 6 dB cable attenuation.
- On chip B3ZS/HDB3 encoder and decoder that can either be enabled or disabled.
- On-chip clock synthesizer generates the appropriate rate clock from a single frequency XTAL.

- Provides low jitter clock outputs for either DS3,E3 or STS-1 rates.
- On-chip clock synthesizer provides the appropriate rate clock from a single 12.288 MHz Clock.
- Provides low jitter output clock.

TRANSMITTER:

- Compliant with Bellcore GR-499, GR-253 and ANSI T1.102 Specification for transmit pulse
- Tri-state Transmit output capability for redundancy applications
- Transmitters can be turned on or off.

JITTER ATTENUATOR:

- On chip advanced crystal-less Jitter Attenuator.
- Jitter Attenuator can be selected in Receive or Transmit paths.
- 16 or 32 bits selectable FIFO size.
- Meets the Jitter and Wander specifications described in T1.105.03b,ETSI TBR-24, Bellcore GR-253 and GR-499 standards.
- Jitter Attenuators can be disabled.

CONTROL AND DIAGNOSTICS:

- 5 wire Serial Microprocessor Interface for control and configuration.
- Supports optional internal Transmit Driver Monitoring.
- PRBS error counter register to accumulate errors.
- Hardware Mode for control and configuration.
- Supports Local, Remote and Digital Loop-backs.
- Single 3.3 V ± 5% power supply.
- 5 V Tolerant I/O.
- Available in 100 pin TQFP.
- -40℃ to 85℃ Industrial Temperature Range.

APPLICATIONS

- E3/DS3 Access Equipment.
- STS1-SPE to DS3 Mapper.
- DSLAMs.
- Digital Cross Connect Systems.
- CSU/DSU Equipment.
- Routers.
- Fiber Optic Terminals.

FIGURE 1. BLOCK DIAGRAM OF THE XRT 75L02

SDI SDO Serial ĪNT Processor SCIk Interface cs

CLK_OUT E3Clk.DS3Clk. STS-1Clk RLOL **RxON** RESET **RxClkINV** Clock HOST/HW Invert RxClk Peak Detector Synthesizer STS-1/DS3 HDB3/ **RPOS** REQEN Clock & Data Jitter Slicer B3ZS AGC/ RNEG/ RTIP Recovery Attenuator Decoder Equalizer RRING LCV LOS SR/DR → Remote Detector Local LoopBack LLB **RLB** LoopBack **RLOS** JATx/Rx TTIP · **TPOS** HDB3/ Line Tx .litter B3ZS Driver Timing **TNEG** MUX Pulse TRING Attenuator Control Shaping TxClk TAOS MTIP Device MRING TxLEV Monitor Control TxON DMO ◀ Note: Serial Processor Interface input pins are shared by in "Host" Mode and redefined in the "Hardware" Mode.

TRANSMIT INTERFACE CHARACTERISTICS

- Accepts either Single-Rail or Dual-Rail data from Terminal Equipment and generates a bipolar signal to the line
- Integrated Pulse Shaping Circuit.
- Built-in B3ZS/HDB3 Encoder (which can be disabled).
- Accepts Transmit Clock with duty cycle of 30%-70%.
- Generates pulses that comply with the ITU-T G.703 pulse template for E3 applications.
- Generates pulses that comply with the DSX-3 pulse template, as specified in Bellcore GR-499-CORE and ANSI T1.102 1993.
- Generates pulses that comply with the STSX-1 pulse template, as specified in Bellcore GR-253-CORE.
- Transmitter can be turned off in order to support redundancy designs.

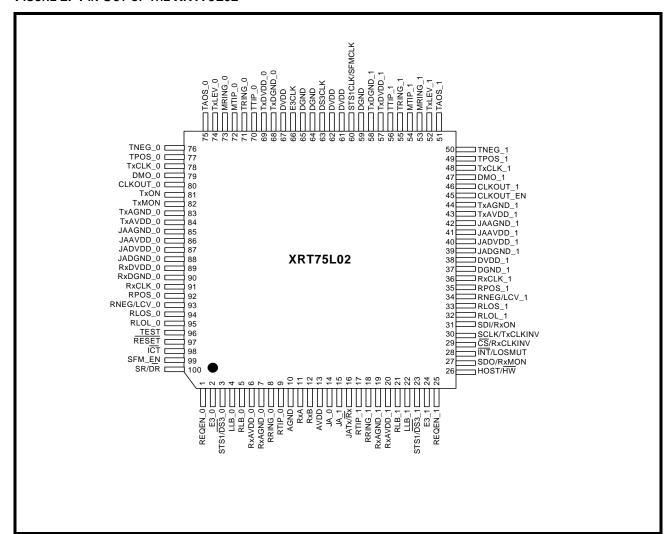
RECEIVE INTERFACE CHARACTERISTICS

- Integrated Adaptive Receive Equalization for optimal Clock and Data Recovery.
- Declares and Clears the LOS defect per ITU-T G.775 requirements for E3 and DS3 applications.
- Meets Jitter Tolerance Requirements, as specified in ITU-T G.823_1993 for E3 Applications.
- Meets Jitter Tolerance Requirements, as specified in Bellcore GR-499-CORE for DS3 Applications.
- Declares Loss of Signal (LOS) and Loss of Lock (LOL) Alarms.
- Built-in B3ZS/HDB3 Decoder (which can be disabled).



- Recovered Data can be muted while the LOS Condition is declared.
- Outputs either Single-Rail or Dual-Rail data to the Terminal Equipment.

FIGURE 2. PIN OUT OF THE XRT75L02



ORDERING INFORMATION

PART NUMBER	PACKAGE	OPERATING TEMPERATURE RANGE
XRT75L02IV	14mm x 14mm 100 Pin TQFP	-40°C to +85°C

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PIN DESCRIPTIONS (BY FUNCTION)

TRANSMIT INTERFACE

Pin#	SIGNAL NAME	Түре	DESCRIPTION
81	TxON	I	Transmitter ON Input :
			This input pin is used to either enable or disable the Transmit Output Driver.
			"Low" - Disables the Transmit Output Driver. In this setting, the TTIP and TRING output pins will be tri-stated.
			"High" - Enables the Transmit Output Driver. In this setting, the TTIP and TRING output pins will be enabled.
			NOTES:
			 Even when the XRT75L02 is configured in HOST mode, this pin will be active. To enable software control of the Transmit Output Driver output, pull this pin "High".
			When the Transmitter is turned off either in Host or Hardware mode, the TTIP and TRing outputs are Tri-stated.
			3. This pins are internally pulled "High"
78	TxCLK_0	I	Transmit Clock Input for TPOS and TNEG - Channel 0:
48	TxCLK_1		Transmit Clock Input for TPOS and TNEG - Channel 1:
			The frequency accuracy of this input clock must be of nominal bit rate \pm 20 ppm. The duty cycle can be 30%-70%.
			By default, input data is sampled on the falling edge of TxCLK when input data is changing on the rising edge of TxCLK
76	TNEG_0	I	Transmit Negative Data Input - Channel 0:
50	TNEG_1		Transmit Negative Data Input - Channel 1:
			In Dual-rail mode, these pins are sampled on the falling or rising edge of TxCLK_n
			NOTE: These input pins are ignored and must be grounded if the Transmitter Section is configured to accept Single-Rail data from the Terminal Equipment.
77	TPOS_0	I	Transmit Positive Data Input - Channel 0:
49	TPOS_1		Transmit Positive Data Input - Channel 1:
			By default sampled on the falling edge of TxCLK
70	TTIP_0	0	Transmit TTIP Output - Channel 0:
56	TTIP_1		Transmit TTIP Output - Channel 1:
			These pins along with TRING transmit bipolar signals to the line using a 1:1 transformer.
71	TRING_0	0	Transmit Ring Output - Channel 0:
55	TRING_1		Transmit Ring Output - Channel 1:
			These pins along with TTIP transmit bipolar signals to the line using a 1:1 transformer.



TRANSMIT INTERFACE

Pin#	SIGNAL NAME	Түре	DESCRIPTION	
30	TxClkINV/ SClk	I	Hardware Mode: Transmit Clock Invert Host Mode: Serial Clock Input: Function of this pin depends on whether the XRT75L02 is configured to operate in Hardware mode or Host mode. In Hardware mode, setting this input pin "High" configures all the Transmitters to sample the TPOS_n and TNEG_n data on the rising edge of the TxClk_n . Notes: 1. If the XRT75L02 is configured in HOST mode, this pin functions as SClk input pin (please refer to the pin description for Microprocessor interface).	
82	TxMON	I	Transmitter Monitor: When this pin is pulled "High", MTIP and MRING are connected internally to TTIP and TRING and allows self monitoring of the transmitter.	
74 52	TxLEV_0 TxLEV_1			
75 51	TAOS_0 TAOS_1	I	Transmit All Ones Select - Channel 0: Transmit All Ones Select - Channel 1: A "High" on this pin causes the Transmitter Section of Channel_n to generate and transmit a continuous AMI all "1's" pattern onto the line. The frequency of this "1's" pattern is determined by TxClk_n. Notes: 1. This input pin is ignored if the XRT75L02 is operating in the HOST Mode and should be tied to GND. 2. Analog Loopback and Remote Loopback have priority over request. 3. This pin is internally pulled down.	

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RECEIVE INTERFACE

Pin#	SIGNAL NAME	Түре	DESCRIPTION
1 25	REQEN_0 REQEN_1	ı	Receive Equalization Enable Input - Channel 0: Receive Equalization Enable Input - Channel 1: Setting this input pin "High" enables the Internal Receive Equalizer of Channel_n. Setting this pin "Low" disables the Internal Receive Equalizer. Notes: 1. This input pin is ignored and should be connected to GND if the XRT75L02 is operating in the HOST Mode 2. This pin is internally pulled down.
31	RxON/ SDI	I	Hardware Mode: Receiver Turn ON Input Host Mode: Serial Data Input: Function of this pin depends on whether the XRT75L02 is configured to operate in Hardware mode or Host mode. In Hardware mode, setting this input pin "High" turns on and enables the Receivers of all the channels. Notes: 1. If the XRT75L02 is configured in HOST mode, this pin functions as SDI input pin (please refer to the pin description for Microprocessor Interface) 2. This pin is internally pulled down.
27	RxMON/ SDO	I	Hardware Mode: Receive Monitoring Mode Host Mode: Serial Data Output: In Hardware mode, when this pin is tied "High" all 2 channels configure into monitoring channels. In the monitoring mode, the Receiver is capable of monitoring the signals with 20 dB flat loss plus 6 dB cable attenuation. This allows monitoring very weak signal, however the internal LOS circuitry is suppressed and LOS will never assert nor LOS be declared when operating under this mode. In HOST Mode each channel can be independently configured to be a monitoring channel by setting the bits in the channel control registers. Note: If the XRT75L02 is configured in HOST mode, this pin functions as SDO pin (please refer to the pin description for the Microprocessor Interface).
91 36	RxCLK_0 RXCLK_1	0	Receive Clock Output - Channel 0: Receive Clock Output - Channel 1: By default, RPOS and RNEG data sampled on the rising edge RxCLK Set the RxCLKINV bit or tie RClkINV pin "High" to sample RPOS/RNEG data on the falling edge of RxCLK
92 35	RPOS_0 RPOS_1	0	Receive Positive Data Output - Channel 0: Receive Positive Data Output - Channel 1: Note: If the B3ZS/HDB3 Decoder is enabled in Single-rail mode, then the zero suppression patterns in the incoming line signal (such as: "00V", "000V", "B0V", "B00V") is removed and replaced with '0'.



RECEIVE INTERFACE

Pin#	SIGNAL NAME	Түре	DESCRIPTION			
93 34	RNEG_0/LCV_0 RNEG_1/LCV_1	0	Receive Negative Data Output/Line Code Violation Indicator - Channel 0:			
			Receive Negative Data Output/Line Code Violation Indicator - Channel 1:			
			In Dual Rail mode, a negative pulse is output through RNEG.			
			Line Code Violation Indicator - Channel n:			
			If configured in Single Rail mode then Line Code Violation will be output.			
8	RRING_0	I	Receive Ring Input - Channel 0:			
18	RRING_1		Receive Ring Input - Channel 1:			
			These pins along with RTIP receive the bipolar line signal from the remote DS3/E3/STS-1 Terminal.			
9	RTIP_0	I	Receive TIP Input - Channel 0:			
17	RTIP_1		Receive TIP Input - Channel 1:			
			These pins along with RRING receive the bipolar line signal from the Remote DS3/E3/STS-1 Terminal.			
29	RxClkINV/	I	Hardware Mode: RxClk INVERT			
	CS		Host Mode: Chip Select:			
			Function of this pin depends on whether the XRT75L02 is configured to operate in Hardware mode or Host mode.			
			In Hardware mode, setting this input pin "High" configures the Receiver Section of all channels to invert the RxClk_n output signals and outputs the recovered data via RPOS_n and RNEG_n on the falling edge of RxClk_n.			
			NOTE: If the XRT75L02 is configured in HOST mode, this pin functions as CS input pin (please refer to the pin description for Microprocessor Interface).			

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CLOCK INTERFACE

Pin#	SIGNAL NAME	Түре	DESCRIPTION
66	E3CLK	I	E3 Clock Input (34.368 MHz ± 20 ppm): If any of the channels is configured in E3 mode, a reference clock 34.368 MHz is applied on this pin.
			Note: In single frequency mode, this reference clock is not required.
63	DS3CLK	I	DS3 Clock Input (44.736 MHz ± 20 ppm):
			If any of the channels is configured in DS3 mode, a reference clock 44.736 MHz. is applied on this pin.
			Note: In single frequency mode, this reference clock is not required.
60	STS-1CLK/ 12M	I	STS-1 Clock Input (51.84 MHz ± 20 ppm):
			If any of the channels is configured in STS-1 mode, a reference clock 51.84 MHz is applied on this pin
			In Single Frequency Mode, a reference clock of 12.288 MHz \pm 20 ppm is connected to this pin and the internal clock synthesizer generates the appropriate clock frequencies based on the configuration of the channels in E3, DS3 or STS-1.
99	SFM_EN	I	Single Frequency Mode Enable:
			Tie this pin "High" to enable the Single Frequency Mode. A reference clock of 12.288 MHz ± 20 ppm is applied. This offers the flexibility of using a low cost reference clock and configures the board for either E3 or DS3 or STS-1 without the need to change any components on the board.
			In the Single Frequency Mode (SFM) an output clock is provided for each channel if the CLKOUT_EN bit is set or CLKOUT_EN pin tied "High".
			Tie this pin "Low" if single frequency mode is not selected. In this case, the appropriate reference clocks must be provided.
			Note: This pin is internally pulled down
80	CLKOUT_0	0	Clock output for channel 0
46	CLKOUT_1		Clock output for channel 1
			Low jitter clock is output for each channel based on the mode selection (E3,DS3 or STS-1) if the CLK_EN_n bit is set in the control register or CLKOUT_EN pin is tied "High".
			This eliminates the need for a separate clock source for the framer.
			Notes:
			This clock output is only available in SFM mode.
			The maximum drive capability for the clockouts is 16 mA.
45	CLKOUT_EN	I	Clock Output Enable in Single Frequency Mode: Tie this pin "High" to enable the output clocks via the CLKOUT pins.



CONTROL AND ALARM INTERFACE

Pin#	SIGNAL NAME	Түре	DESCRIPTION
73	MRING_0	I	Monitor Ring Input - Channel 0:
53	MRING_1		Monitor Ring Input - Channel 1:
			The bipolar line output signal from TRING_n is connected to this pin via a 270 Ω resistor to check for line driver failure.
			Note: This pin is internally pulled "High".
72	MTIP_0	I	Monitor Tip Input - Channel 0:
54	MTIP_1		Monitor Tip Input - Channel 1:
			The bipolar line output signal from TTIP_n is connected to this pin via a 270-ohm resistor to check for line driver failure.
			Note: This pin is internally pulled "High".
79	DMO_0	0	Drive Monitor Output - Channel 0:
47	DMO_1		Drive Monitor Output - Channel 1:
			If MTIP_n and MRING_n has no transition pulse for 128 ± 32 TxCLK_n cycles, DMO_n goes "High" to indicate the driver failure. DMO_n output stays "High" until the next AMI signal is detected.
94	RLOS_0	0	Receive Loss of Signal Output Indicator - Channel 0:
33	RLOS_1		Receive Loss of Signal Output Indicator - Channel 1:
			This output pin toggles "High" if the receiver has detected a Loss of Signal Con-
			dition.
			The criteria for declaring /clearing an LOS Condition depends upon whether it is operating in the E3 or STS-1/DS3 Mode.
95	RLOL_0	0	Receive Loss of Lock Output Indicator - Channel 0:
32	RLOL_1		Receive Loss of Lock Output Indicator - Channel 1:
			This output pin toggles "High" if a Loss of Lock Condition is detected. LOL (Loss of Lock) condition occurs if the recovered clock frequency deviates from the Reference Clock frequency (available at either E3CLK or DS3CLK or STS-1CLK input pins) by more than 0.5%.
11	RXA	***	External Resistor of 3 K Ω ± 1%.
			Should be connected between RxA and RxB for internal bias.
12	RXB	***	External Resistor of 3K Ω ±1%.
			Should be connected between RxA and RxB for internal bias.
98	ĪCT	I	In-Circuit Test Input:
			Setting this pin "Low" causes all digital and analog outputs to go into a high-impedance state to allow for in-circuit testing. For normal operation, tie this pin "High".
			Note: This pin is internally pulled "High".
96	TEST	****	Factory Test Pin
			Note: This pin must be connected to GND for normal operation.



CONTROL AND ALARM INTERFACE

28	LOSMUT/	I/O	Hardware Mo	ode: MUTE-u _l	pon-LOS Enab	le Input	
	ĪNT		Host Mode:	Interrupt Ou	out:		
			recovered da	ta on the RP	OS_n and RNE	ifigures all the channel EG_n whenever one of RNEG_n outputs are pu	the channels
			Muting of the in Host Mode.		can be configur	red/controlled on a per	channel basis
					•	IOST mode, this pin fun tion for the Microproces	
4	LLB_0	I	Local Loop	-back - Cha	nnel 0:		
22	LLB_1		Local Loop	-back - Cha	nnel 1:		
			This input pin	along with RI	_B_n configures	s different Loop-Back m	odes.
			A "High" on the in the Analog			w" configures Channel_	_n to operate
			A "High" on the in the Digital L			gh" configures Channel	_n to operate
				nput pin is igno OST Mode.	ored and should	d be connected to GND	if operating in
5	RLB_0	I	Remote Loc	p-back - Cl	hannel 0:		
21	RLB_1		Remote Loc	p-back - Cl	hannel 1:		
						different Loop-Back mo	
			A "High" on the the Remote L			r" configures Channel_r	to operate in
			A "High" on the in the Digital I			h" configures Channel	_n to operate
			-	•			
				RLB_n	LLB_n	Loopback Mode	
				0	0	Normal Operation	
				0	1	Analog Local	
				1	0	Remote	
				1	1	Digital	
				input pin is ating in the HC	•	hould be connected to	o GND when



MODE SELECT

Pin#	SIGNAL NAME	Түре	DESCRIPTION
2 24	E3_0 E3_1	I	E3 Mode Select Input A "High" on this pin configures in E3 mode. A "Low" on this pin configures in either STS-1 or DS3 mode depending on the settings on pins 3 and 23 Notes: 1. This pin is internally pulled down 2. This pin is ignored if configured to operate in HOST mode.
3 23	STS1/DS3 _0 STS1/DS3 _1	I	STS-1/DS3 Select Input A "High" on these pins configures in STS-1 mode. A "Low" on these pins configures in DS3 mode. These pins are ignored if the E3_n pins are set to "High". Notes: 1. This pin is internally pulled down 2. This pin is ignored if configured to operate in HOST mode.
26	HOST/HW	I	Host/Hardware Mode: Tie this pin "High" to configure in Host mode and "Low" for Hardware mode.
100	SR/DR	I	Single-Rail/Dual-Rail Select: Setting this "High" configures both the Transmitter and Receiver to operate in Single-rail mode and also enables the B3ZS/HDB3 Encoder and Decoder. In Single-rail mode, TNEG_n pin should be grounded. Setting this "Low" configures both the Transmitter and Receiver to operate in Dual-rail mode and disables the B3ZS/HDB3 Encoder and Decoder. Note: This pin is internally pulled down.

MICROPROCESSOR SERIAL INTERFACE - (HOST MODE)

Pin#	SIGNAL NAME	Түре	DESCRIPTION		
29	CS RxCLKINV	I	Microprocessor Serial Interface - Chip Select Tie this "Low" to enable the communication with the Microprocessor Serial Interface. Note: If configured in Hardware Mode, this pin functions as RxClkINV.		
30	SCLK TxCLKINV	I	Serial Interface Clock Input The data on the SDI pin is sampled on the rising edge of this signal. Additionally, during Read operations the Microprocessor Serial Interface updates the SDO output on the falling edge of this signal. Note: If configured in Hardware Mode, this pin functions as TxClkINV.		
31	SDI RxON	I	Serial Data Input: Data is serially input through this pin. The input data is sampled on the rising edge of the SCIk Notes: 1. This pin is internally pulled down 2. If configured in Hardware Mode, this pin functions as RxON.		



MICROPROCESSOR SERIAL INTERFACE - (HOST MODE)

Pin#	SIGNAL NAME	Түре	DESCRIPTION
27	SDO RxMON	I/O	Serial Data Output: This pin serially outputs the contents of the specified Command Register during Read Operations. The data is updated on the falling edge of the SClk and this pin is tri-stated upon completion of data transfer. Note: If configured in Hardware Mode, this pin functions as RxMON.
97	RESET	I	Register Reset: Setting this input pin "Low" causes to reset the contents of the Command Registers to their default settings and default operating configuration Note: This pin is internally pulled up.
28	INT LOSMUT	I/O	INTERRUPT Output: A transition to "Low" indicates that an interrupt has been generated. The interrupt function can be disabled by setting the interrupt enable bit to "0" in the Channel Control Register. Notes: 1. In Hardware mode, this pin functions as LOSMUT. 2. This pin will remain asserted "Low" until the interrupt is serviced.

JITTER ATTENUATOR INTERFACE

PIN#	SIGNAL NAME	Түре			DESCRIPT	TION			
15	JA1	I	In Hardware N	Jitter Attenuator Select 1: In Hardware Mode, this pin along with the pin JA0 configures the Jitter Attenuator as shown in the table.					
				JA0	JA1	Mode			
			0 0 16 bit FIFO						
				0 1 32 bit FIFO					
				1	0	0 Disable Jitter Attenuator			
				1	1	Disable Jitter Attenuator			
			Note: This p	in is internally	pulled down.		•		
16	JATx/Rx	I	Jitter Attenuator Path Select In Hardware Mode, tie this pin "High" to select the Jitter Attenuator in the Transmit Path . Connect this pin "Low" to select the Jitter Attenuator in the Receive Path. This applies to all channels. Note: This pin is internally pulled down.						
14	JA0	I	Jitter Attenuator Select 0: In Hardware Mode, this pin along with pin JA1 configures the Jitter Attenuator as shown in the above table. Note: This pin is internally pulled down.						



ANALOG POWER AND GROUND

Pin#	SIGNAL NAME	TYPE	DESCRIPTION
84	TxAVDD_0	****	Transmitter Analog 3.3 V ± 5% VDD - Channel 0
43	TxAVDD_1	****	Transmitter Analog 3.3 V ± 5% VDD - Channel 1
83	TxAGND_0	****	Transmitter Analog GND - Channel 0
44	TxAGND_1	***	Transmitter Analog GND - Channel 1
6	RxAVDD_0	***	Receiver Analog 3.3 V ± 5% VDD - Channel 0
20	RxAVDD_1	****	Receiver Analog 3.3 V ± 5% VDD - Channel 1
7	RxAGND_0	****	Receiver Analog GND - Channel_0
19	RxAGND_1	****	Receive Analog GND - Channel 1
86	JAAVDD_0	****	Analog 3.3 V ± 5% VDD - Channel 0
41	JAAVDD_1	****	Analog 3.3 V ± 5% VDD - Channel 1
85	JAAGND_0	****	Analog GND - Channel 0
42	JAAGND_1	****	Analog GND - Channel 1
13	AVDD	***	Analog 3.3 V ± 5% VDD
10	AGND	****	Analog GND

DIGITAL POWER AND GROUND

Pin#	SIGNAL NAME	Түре	DESCRIPTION
69	TxVDD_0	****	Transmitter 3.3 V ± 5% VDD Channel 0
57	TxVDD_1	****	Transmitter 3.3 V ± 5% VDD Channel 1
68	TxGND_0	****	Transmitter GND - Channel 0
58	TxGND_1	****	Transmitter GND - Channel 1
89	RxDVDD_0	****	Receiver 3.3 V ± 5% VDD - Channel 0
38	RxDVDD_1	****	Receiver 3.3 V ± 5% VDD - Channel 1
90	RxDGND_0	****	Receiver Digital GND - Channel 0
37	RxDGND_1	****	Receiver Digital GND - Channel 1
87	JADVDD_0	****	Jitter Attenuator 3.3 V ± 5% VDD - Channel 0
40	JADVDD_1	****	Jitter Attenuator 3.3 V ± 5% VDD - Channel 188
88	JADGND_0	****	Jitter Attenuator Digital GND - Channel 0
39	JADGND_1	****	Jitter Attenuator Digital GND - Channel 1
61	DVDD	****	Digital VDD 3.3.v ± 5%
62	DVDD	***	Digital VDD 3.3.v ± 5%

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DIGITAL POWER AND GROUND

Pin#	SIGNAL NAME	Түре	DESCRIPTION
67	DVDD	****	Digital VDD 3.3.v ± 5%
59	DGND	****	Digital GND
64	DGND	****	Digital GND
65	DGND	****	Digital GND



1.0 ELECTRICAL CHARACTERISTICS

TABLE 1: ABSOLUTE MAXIMUM RATINGS

SYMBOL	PARAMETER	MIN	MAX	UNITS	COMMENTS
V_{DD}	Supply Voltage	-0.5	6.0	V	Note 1
V _{IN}	Input Voltage at any Pin	-0.5	5+0.5	V	Note 1
I _{IN}	Input current at any pin		100	mA	Note 1
S _{TEMP}	Storage Temperature	-65	150	0C	Note 1
A _{TEMP}	Ambient Operating Temperature	-40	85	0C	linear airflow 0 ft./min
ThetaJA	Thermal Resistance		20	0C/W	linear air flow 0ft/min
ThetaJC			6	0C/W	
M _{LEVL}	Exposure to Moisture	5		level	EIA/JEDEC JESD22-A112-A
ESD	ESD Rating		2000	V	Note 2

Notes:

- 1. Exposure to or operating near the Min or Max values for extended period may cause permanent failure and impair reliability of the device.
- 2. ESD testing method is per MIL-STD-883D,M-3015.7

TABLE 2: DC ELECTRICAL CHARACTERISTICS:

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNITS
DV_DD	Digital Supply Voltage	3.135	3.3	3.465	V
AV_{DD}	Analog Supply Voltage	3.135	3.3	3.465	V
I _{CC}	Supply current (Measured while transmitting and receiving all 1's)		260	340	mA
P _{DD}	Power Dissipation		860	1200	mW
V _{IL}	Input Low Voltage			0.8	V
V _{IH}	Input High Voltage	2.0		5.0	V
V _{OL}	Output Low Voltage, I _{OUT} = - 4mA			0.4	V
V _{OH}	Output High Voltage, I _{OUT} = 4 mA	2.4			V
Ι <u>ι</u>	Input Leakage Current ¹			±10	μΑ
C _I	Input Capacitance			10	pF
C _L	Load Capacitance			10	pF

Notes:

- 1. Not applicable for pins with pull-up or pull-down resistors.
- 2. The Digital inputs and outputs are TTL 5V compliant.



2.0 TIMING CHARACTERISTICS

FIGURE 3. TYPICAL INTERFACE BETWEEN TERMINAL EQUIPMENT AND THE XRT75L02 (DUAL-RAIL DATA)

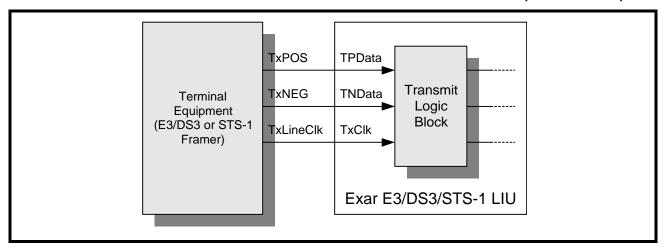
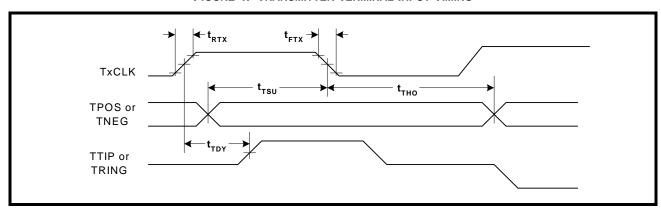


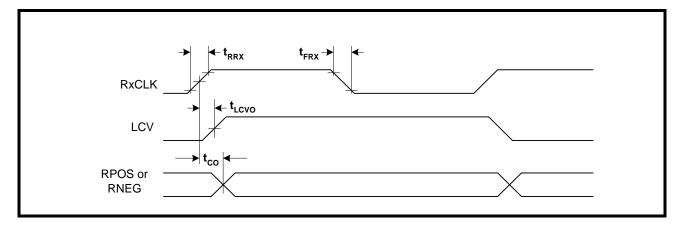
FIGURE 4. TRANSMITTER TERMINAL INPUT TIMING



SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
TxClk	Duty Cycle E3 DS3 STS-1	30	50 34.368 44.736 51.84	70	% MHz MHz MHz
t _{RTX}	TxCLK Rise Time (10% to 90%)			4	ns
t _{FTX}	TxCLKFall Time (10% to 90%)			4	ns
t _{TSU}	TPOS/TNEG to TxCLK falling set up time	3			ns
t _{THO}	TPOS/TNEG to TxCLK falling hold time	3			ns
t _{TDY}	TTIP/TRINGto TxCLK rising propagation delay time		8		ns

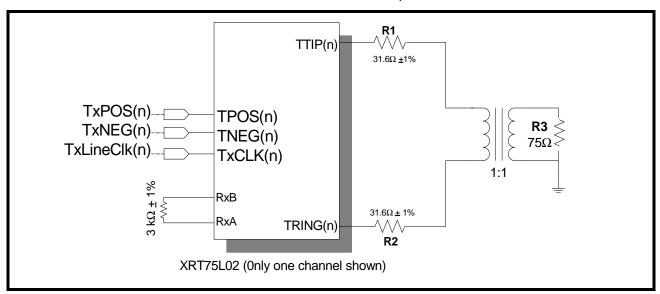


FIGURE 5. RECEIVER DATA OUTPUT AND CODE VIOLATION TIMING



SYMBOL	PARAMETER	MIN	TYP	MAX	UNITS
RxClk	Duty Cycle	45	50	55	%
	E3		34.368		MHz
	DS3		44.736		MHz
	STS-1		51.84		MHz
t _{RRX}	RxCLK rise time (10% o 90%)		2	4	ns
t _{FRX}	RxCLKfalling time (10% to 90%)		2	4	ns
t _{CO}	RxCLKto RPOS/RNEG delay time			4	ns
t _{LCVO}	RxCLK to rising edge of LCV output delay		2.5		ns

FIGURE 6. TRANSMIT INTERFACE CIRCUIT FOR E3, DS3 AND STS-1 RATES



REV. 1.0.3

3.0 LINE SIDE CHARACTERISTICS:

3.1 E3 line side parameters:

The XRT75L02 line output at the transformer output meets the pulse shape specified in ITU-T G.703 for 34.368 Mbits/s operation. The pulse mask as specified in ITU-T G.703 for 34.368 Mbits/s is shown in Figure 7.

17 ns -(14.55 + 2.45) V = 100% _Nominal Pulse 50% 14.55ns 12.1ns _____ (14.55 - 2.45) 0%

FIGURE 7. PULSE MASK FOR E3 (34.368 MBITS/S) INTERFACE AS PER ITU-T G.703

TABLE 3: E3 TRANSMITTER LINE SIDE OUTPUT AND RECEIVER LINE SIDE INPUT SPECIFICATIONS

PARAMETER	MIN	TYP	MAX	UNITS				
TRANSMITTER LINE SIDE OUTPUT CHARACTERISTICS								
Transmit Output Pulse Amplitude (Measured at secondary of the transformer)	0.90	1.00	1.10	V_{pk}				
Transmit Output Pulse Amplitude Ratio	0.95	1.00	1.05					
Transmit Output Pulse Width	12.5	14.55	16.5	ns				
RECEIVER LINE SIDE INPUT CHARAC	RECEIVER LINE SIDE INPUT CHARACTERISTICS							
Receiver Sensitivity (length of cable)		1200		feet				
Interference Margin	-20	-16		dB				
Jitter Tolerance @ Jitter Frequency 800KHz	0.15	0.30		Ul _{PP}				
Signal level to Declare Loss of Signal			-35	dB				
Signal Level to Clear Loss of Signal	-15			dB				
Occurence of LOS to LOS Declaration Time	10		255	UI				
Termination of LOS to LOS Clearance Time	10		255	UI				

Note: The above values are at

TA = 25° C and $V_{DD} = 3.3 \text{ V} \pm 5\%$.



FIGURE 8. BELLCORE GR-253 CORE TRANSMIT OUTPUT PULSE TEMPLATE FOR SONET STS-1 APPLICATIONS

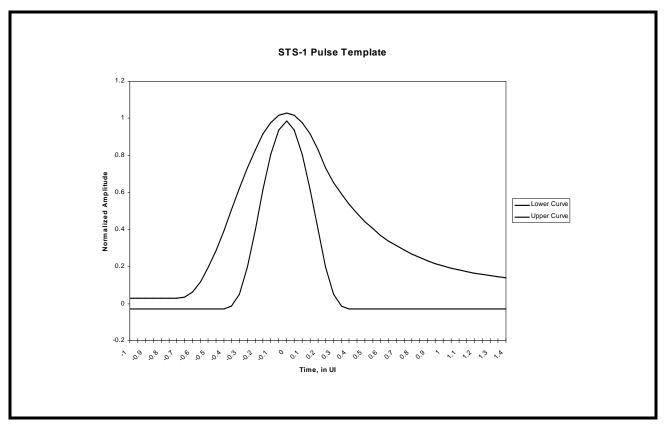


TABLE 4: STS-1 PULSE MASK EQUATIONS

TIME IN UNIT INTERVALS	Normalized Amplitude
LOWER	CURVE
-0.85 ≤ T ≤ -0.38	- 0.03
-0.38 ≤ T ≤ 0.36	$0.5\left[1+\sin\frac{\pi}{2}\left(1+\frac{T}{0.18}\right)\right]-0.0$
0.36 ≤ T ≤ 1.4	- 0.03
UPPER	CURVE
-0.85 ≤ T ≤ -0.68	0.03
-0.68 ≤ T ≤ 0.26	$0.5 \left[1 + \sin \frac{\pi}{2} \left(1 + \frac{T}{0.34} \right) \right] + 0.0$
0.26 ≤ T ≤ 1.4	$0.1 + 0.61 \times e^{-2.4[T-0.26]}$



TABLE 5: STS-1 TRANSMITTER LINE SIDE OUTPUT AND RECEIVER LINE SIDE INPUT SPECIFICATIONS (GR-253)

PARAMETER	Min	Түр	Max	Units				
TRANSMITTER LINE SIDE OUTPUT CHARACTERISTICS								
Transmit Output Pulse Amplitude (measured with TxLEV = 0)		0.75		V _{pk}				
Transmit Output Pulse Amplitude (measured with TxLEV = 1)	0.90	1.00	1.10	V _{pk}				
Transmit Output Pulse Width	8.6	9.65	10.6	ns				
Transmit Output Pulse Amplitude Ratio	0.90	1.00	1.10					
RECEIVER LINE SIDE INPUT CHARACTERISTICS								
Receiver Sensitivity (length of cable)	900	1100		feet				
Jitter Tolerance @ Jitter Frequency 400 KHz	0.15	0.79		Ul _{pp}				

Note: The above values are at

TA = 25° C and V_{DD} = $3.3 \text{ V} \pm 5\%$.

FIGURE 9. TRANSMIT OUPUT PULSE TEMPLATE FOR DS3 AS PER BELLCORE GR-499

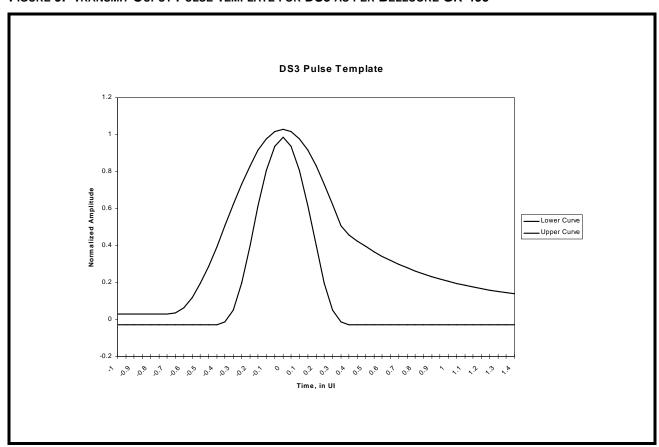




TABLE 6: DS3 PULSE MASK EQUATIONS

TIME IN UNIT INTERVALS	Normalized Amplitude					
LOWER CURVE						
$-0.85 \le T \le -0.36$	- 0.03					
-0.36 ≤ T ≤ 0.36	$0.5\left[1+\sin\frac{\pi}{2}\left(1+\frac{T}{0.18}\right)\right]-0.0$					
0.36 ≤ T ≤ 1.4	- 0.03					
UPPER	CURVE					
$-0.85 \le T \le -0.68$	0.03					
-0.68 ≤ T ≤ 0.36	$0.5 \left[1 + \sin \frac{\pi}{2} \left(1 + \frac{T}{0.34} \right) \right] + 0.0$					
0.36 ≤ T ≤ 1.4	$0.08 + 0.407 \text{ x e}^{-1.84[\text{T-}0.36]}$					

TABLE 7: DS3 TRANSMITTER LINE SIDE OUTPUT AND RECEIVER LINE SIDE INPUT SPECIFICATIONS (GR-499)

PARAMETER	Min	Түр	Max	Units
TRANSMITTER LINE SIDE OUTPUT C	HARACTERISTI	cs	•	•
Transmit Output Pulse Amplitude (measured with TxLEV = 0)		0.75		V_{pk}
Transmit Output Pulse Amplitude (measured with TxLEV = 1)	0.90	1.00	1.10	V _{pk}
Transmit Output Pulse Width	10.10	11.18	12.28	ns
Transmit Output Pulse Amplitude Ratio	0.90	1.00	1.10	
RECEIVER LINE SIDE INPUT CHAP	RACTERISTICS			•
Receiver Sensitivity (length of cable)	900	1100		feet
Jitter Tolerance @ 400 KHz (Cat II)		0.60		Ul _{pp}

Note: The above values are at

 $TA = 25^{0}C$ and $V_{DD} = 3.3V \pm 5\%$.

FIGURE 10. MICROPROCESSOR SERIAL INTERFACE STRUCTURE

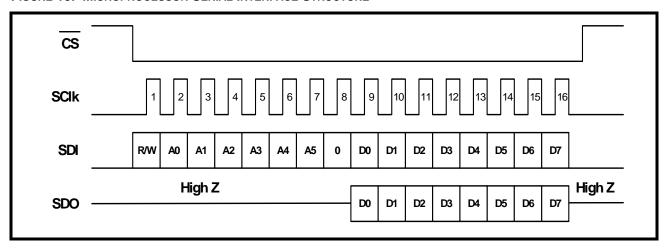


FIGURE 11. TIMING DIAGRAM FOR THE MICROPROCESSOR SERIAL INTERFACE

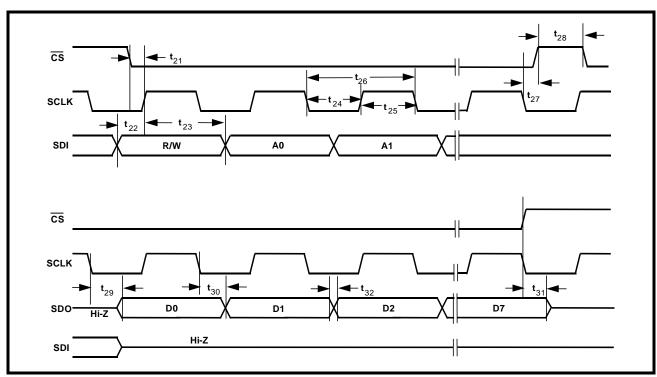




Table 8: Microprocessor Serial Interface Timings ($T_A = 25^0 C$, $V_{DD} = 3.3 V \pm 5\%$ and load = 10pF)

SYMBOL	PARAMETER	Min.	TYP.	Max	Units
t ₂₁	CS Low to Rising Edge of SCIk	5			ns
t ₂₂	SDI to Rising Edge of SCIk	5			ns
t ₂₃	SDI to Rising Edge of SCIk Hold Time	5			ns
t ₂₄	SCIk "Low" Time		25		ns
t ₂₅	SCIk "High" Time		25		ns
t ₂₆	SCIk Period		50		ns
t ₂₇	Falling Edge of SCIk to rising edge of CS	0			ns
t ₂₈	CS "Inactive" Time	50			ns
t ₂₉	Falling Edge of SCIk to SDO Valid Time			20	ns
t ₃₀	Falling Edge of SCIk to SDO Invalid Time			10	ns
t ₃₁	Rising edge of CS to High Z		10		ns
t ₃₂	Rise/Fall time of SDO Output			5	ns

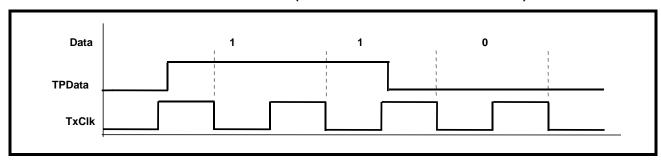
X EXAR

4.0 THE TRANSMITTER SECTION:

The Transmitter Section, within each Channel, accepts TTL/CMOS level signals from the Terminal Equipment in selectable data formats.

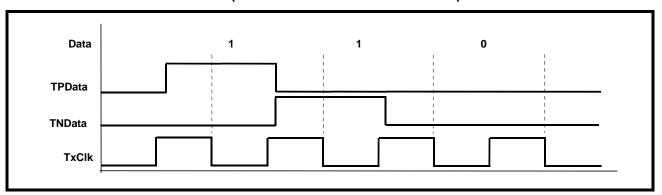
- Convert the CMOS level B3ZS or HDB3 encoded data into pulses with shapes that are compliant with the various industry standard pulse template requirements. Figures 7, 8 and 9 illustrate the pulse template requirements.
- Encode the un-encoded NRZ data into either B3ZS format (for DS3 or STS-1) or HDB3 format (for E3) and convert to pulses with shapes and width that are compliant with industry standard pulse template requirements. Figures 7, 8 and 9 illustrate the pulse template requirements.
- In Single-Rail or un-encoded Non-Return-to-Zero (NRZ) mode, data is input via TPOS in pins while TNEG in pins must be grounded. The NRZ or Single-Rail mode is selected when the SR/DR input pin is "High" (in Hardware Mode) or bit 0 of channel control register is "1" (in Host Mode). Figure 12 illustrates the Single-Rail or NRZ format.

FIGURE 12. SINGLE-RAIL OR NRZ DATA FORMAT (ENCODER AND DECODER ARE ENABLED)



 In Dual-Rail mode, data is input via TPOS_n and TNEG_n pins. TPOS_n contains positive data and TNEG n contains negative data. The SR/DR input pin = "Low" (in Hardware Mode) or bit 0 of channel register = "0" (in Host Mode) enables the Dual-Rail mode. Figure 13 illustrates the Dual-Rail data format.

FIGURE 13. DUAL-RAIL DATA FORMAT (ENCODER AND DECODER ARE DISABLED)



4.1 TRANSMIT CLOCK:

The Transmit Clock applied via TxClk n pins, for the selected data rate (for E3 = 34.368 MHz, DS3 = 44.736 MHz or STS-1 = 51.84 MHz), is duty cycle corrected by the internal PLL circuit to provide a 50% duty cycle clock to the pulse shaping circuit. This allows a 30% to 70% duty cycle Transmit Clock to be supplied.

4.2 **B3ZS/HDB3** ENCODER:

When the Single-Rail (NRZ) data format is selected, the Encoder Block encodes the data into either B3ZS format (for either DS3 or STS-1) or HDB3 format (for E3).

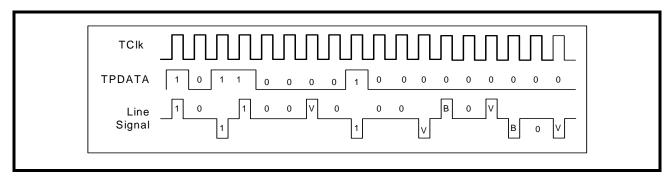
4.2.1 **B3ZS Encoding:**

An example of B3ZS encoding is shown in Figure 14. If the encoder detects an occurrence of three consecutive zeros in the data stream, it is replaced with either B0V or 00V, where 'B' refers to Bipolar pulse



that is compliant with the Alternating polarity requirement of the AMI (Alternate Mark Inversion) line code and 'V' refers to a Bipolar Violation (e.g., a bipolar pulse that violates the AMI line code). The substitution of B0V or 00V is made so that an odd number of bipolar pulses exist between any two consecutive violation (V) pulses. This avoids the introduction of a DC component into the line signal.

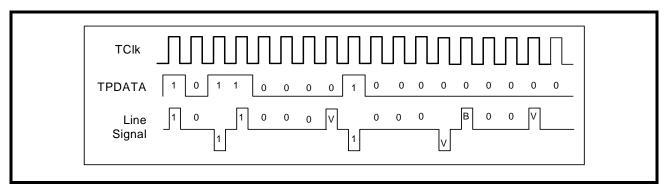
FIGURE 14. B3ZS ENCODING FORMAT



4.2.2 HDB3 Encoding:

An example of the HDB3 encoding is shown in Figure 15. If the HDB3 encoder detects an occurrence of four consecutive zeros in the data stream, then the four zeros are substituted with either 000V or B00V pattern. The substitution code is made in such a way that an odd number of bipolar (B) pulses exist between any consecutive V pulses. This avoids the introduction of DC component into the analog signal.

FIGURE 15. HDB3 ENCODING FORMAT



Notes:

- 1. When Dual-Rail data format is selected, the B3ZS/HDB3 Encoder is automatically disabled.
- 2. In Dual-Rail format, the Bipolar Violations in the incoming data stream is converted to valid data pulses.
- 3. Encoder and Decoder is enabled only in Single-Rail mode.

4.3 TRANSMIT PULSE SHAPER:

The Transmit Pulse Shaper converts the B3ZS encoded digital pulses into a single analog Alternate Mark Inversion (AMI) pulse that meet the industry standard mask template requirements for STS-1 and DS3. See Figures 8 and 9.

For E3 mode, the pulse shaper converts the HDB3 encoded pulses into a single full amplitude square shaped pulse with very little slope. This is illustrated in Figure 7.

The Pulse Shaper Block also includes a Transmit Build Out Circuit, which can either be disabled or enabled by setting the TxLEV_n input pin "High" or "Low" (in Hardware Mode) or setting the TxLEV_n bit to "1" or "0" in the control register (in Host Mode).

For DS3/STS-1 rates, the Transmit Build Out Circuit is used to shape the transmit waveform that ensures that transmit pulse template requirements are met at the Cross-Connect system. The distance between the transmitter output and the Cross-Connect system can be between 0 to 450 feet.



For E3 rate, since the output pulse template is measured at the secondary of the transformer and since there is no Cross-Connect system pulse template requirements, the Transmit Build Out Circuit is always disabled.

4.3.1 Guidelines for using Transmit Build Out Circuit:

If the distance between the transmitter and the DSX3 or STSX-1, Cross-Connect system, is less than 225 feet, enable the Transmit Build Out Circuit by setting the TxLEV_n input pin "Low" (in Hardware Mode) or setting the TxLEV_n control bit to "0" (in Host Mode).

If the distance between the transmitter and the DSX3 or STSX-1 is greater than 225 feet, disable the Transmit Build Out Circuit.

4.3.2 Interfacing to the line:

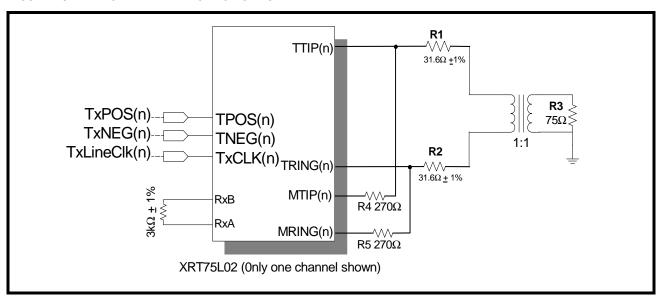
The differential line driver increases the transmit waveform to appropriate level and drives into the 75Ω load as shown in Figure 6.

4.4 Transmit Drive Monitor:

This feature is used for monitoring the transmit line for occurrence of fault conditions such as a short circuit on the line or a defective line driver.

To activate this function, connect MTIP_n pins to the TTIP_n lines via a 270 Ω resistor and MRing_n pins to TRING_n lines via 270 Ω resistor as shown in Figure 16.

FIGURE 16. TRANSMIT DRIVER MONITOR SET-UP.



When the MTIP_n and MRING_n are connected to the TTIP_n and TRING_n lines, the drive monitor circuit monitors the line for transitions. The DMO_n (Drive Monitor Output) will be asserted "Low" as long as the transitions on the line are detected via MTIP_n and MRING_n.

If no transitions on the line are detected for 128 ± 32 TxClk_n periods, the DMO_n output toggles "High" and when the transitions are detected again, DMO_n toggles "Low".

NOTES:

- 1. The Drive Monitor Circuit is only for diagnostic purpose and does not have to be used to operate the transmitter.
- 2. With TxMON pin "High", MTIP and MRING will be internally connected to TTIP and TRING for self-monitoring.



4.5 Transmitter Section On/Off:

The transmitter section of each channel can either be turned on or off. To turn on the transmitter, set the input pin TxON to "High" (in Hardware Mode) or in Host Mode set the TxON_n control bits and tie the TxON pins "High"

When the transmitter is turned off, TTIP_n and TRING_n are tri-stated.

NOTES:

- 1. This feature provides support for Redundancy.
- 2. If configured in Host mode, to permit a system designed for redundancy to quickly shut-off the defective line card and turn on the back-up line card, setting the TxON_n control bits transfers the control to TxON pins.

5.0 THE RECEIVER SECTION:

This section describes the detailed operation of the various blocks in the receiver. The receiver recovers the TTL/CMOS level data from the incoming bipolar B3ZS or HDB3 encoded input pulses.

5.1 AGC/Equalizer:

The Adaptive Gain Control circuit amplifies the incoming analog signal and compensates for the various flat losses and also for the loss at one-half symbol rate. The AGC has a dynamic range of 30 dB.

The Equalizer restores the integrity of the signal and compensates for the frequency dependent attenuation up to 900 feet of coaxial cable (1300 feet for E3). The Equalizer also boosts the high frequency content of the signal to reduce Inter-Symbol Interference (ISI) so that the slicer slices the signal at 50% of peak voltage to generate Positive and Negative data.

The Equalizer can either be "IN" or "OUT" by setting the REQEN_n pin "High" or "Low" (in Hardware Mode) or setting the REQEN n control bit to "1" or "0" (in Host Mode).

RECOMMENDATIONS FOR EQUALIZER SETTINGS:

The Equalizer has two gain settings to provide optimum equalization. In the case of normally shaped DS3/STS-1 pulses (pulses that meet the template requirements) that has been driven through 0 to 900 feet of cable, the Equalizer can be left "IN" by setting the REQEN_n pin to "High" (in Hardware Mode) or setting the REQEN_n control bit to "1" (in Host Mode).

However, for square-shaped pulses such as E3 or for DS3/STS-1 high pulses (that does not meet the pulse template requirements), it is recommended that the Equalizer be left "OUT" for cable length less than 300 feet by setting the REQEN_n pin "Low" (in Hardware Mode) or by setting the REQEN_n control bit to "0" (in Host Mode). This would help to prevent over-equalization of the signal and thus optimize the performance in terms of better jitter transfer characteristics.

Note: The results of extensive testing indicates that even when the Equalizer was left "IN" (REQEN_n = "HIGH"), regardless of the cable length, the integrity of the E3 signal was restored properly over 0 to 12 dB cable loss at Industrial Temperature.

The Equalizer also contain an additional 20 dB gain stage to provide the line monitoring capability of the resistively attenuated signals which may have 20dB flat loss. This capability can be turned on by setting the RxMON_n bits in the control register or by setting the RxMON pin "High". However, asserting or enabling RxMON suppresses the internal LOS circuitry and LOS will never assert nor LOS be declared when operating with RxMON enabled.

5.1.1 Interference Tolerance:

For E3 mode, ITU-T G.703 Recommendation specifies that the receiver be able to recover error-free clock and data in the presence of a sinusoidal interfering tone signal. For DS3 and STS-1 modes, the same recommendation is being used. Figure 17 shows the configuration to test the interference margin for DS3/STS1. Figure 18 shows the set up for E3.

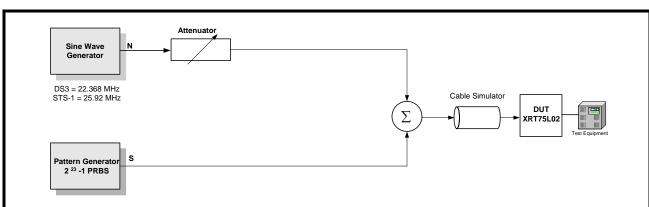


FIGURE 17. INTERFERENCE MARGIN TEST SET UP FOR DS3/STS-1

FIGURE 18. INTERFERENCE MARGIN TEST SET UP FOR E3.

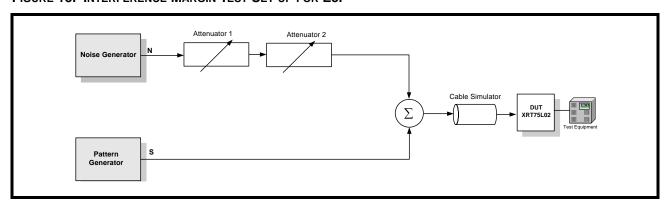


TABLE 9: INTERFERENCE MARGIN TEST RESULTS

Mode	Cable Length (Attenuation)	Interference Tolerance
E3	0 dB	-14 dB
	12 dB	-18 dB
	0 feet	-17 dB
DS3	225 feet	-16 dB
	450 feet	-16dB
	0 feet	-16 dB
STS-1	225 feet	-15 dB
	450 feet	-15 dB

5.2 Clock and Data Recovery:

The Clock and Data Recovery Circuit extracts the embedded clock, from the sliced digital data stream and provides the retimed data to the B3ZS (HDB3) decoder.

The Clock Recovery PLL can be in one of the following two modes:



TRAINING MODE:

In the absence of input signals at RTIP_n and RRING_n pins, or when the frequency difference between the recovered line clock signal and the reference clock applied on the E3/DS3/STS1CLK input pins exceed 0.5%, a Loss of Lock condition is declared by toggling RLOL_n output pin "High" (in Hardware Mode) or setting the RLOL_n bit to "1" in the control registers. Also, the clock output on the RxClk_n pins are the same as the reference clock applied on E3/DS3/STS1CLK pins.

DATA/CLOCK RECOVERY MODE:

In the presence of input line signals on the RTIP_n and RRING_n input pins and when the frequency difference between the recovered clock signal and the reference clock signal is less than 0.5%, the clock that is output on the RxClk_n out pins is the Recovered Clock signal.

5.3 B3ZS/HDB3 Decoder:

The decoder block takes the output from clock and data recovery block and decodes the B3ZS (for DS3 or STS-1) or HDB3 (for E3) encoded line signal and detects any coding errors or excessive zeros in the data stream.

When the input signal violates the B3ZS or HDB3 coding sequence for bipolar violation or contains three (for B3ZS) or four (for HDB3) or more consecutive zeros, an active "High" pulse is generated on the RLCV_n output pins to indicate line code violation.

NOTE: In Single- Rail (NRZ) mode, the decoder is bypassed.

5.4 LOS (Loss of Signal) Detector:

5.4.1 DS3/STS-1 LOS Condition:

A Digital Loss of SIgnal (DLOS) condition occurs when a string of 175 ± 75 consecutive zeros occur on the line. When the DLOS condition occurs, the DLOS_n bit is set to "1" in the status control register. DLOS condition is cleared when the detected average pulse density is greater than 33% for 175 ± 75 pulses.

Analog Loss of Signal (ALOS) condition occurs when the amplitude of the incoming line signal is below the threshold as shown in the Table 10. The status of the ALOS condition is reflected in the ALOS_n status control register.

RLOS is the logical OR of the DLOS and ALOS states. When the RLOS condition occurs the RLOS_n output pin is toggled "High" and the RLOS_n bit is set to "1" in the status control register.

TABLE 10: THE ALOS (ANALOG LOS) DECLARATION AND CLEARANCE THRESHOLDS FOR A GIVEN SETTING OF REQEN (DS3 AND STS-1 APPLICATIONS)

APPLICATION	REQEN SETTING	SIGNAL LEVEL TO DECLARE ALOS	SIGNAL LEVEL TO CLEAR ALOS
DS3	0	<u><</u> 17 mV	≥70 mV
	1	<u><</u> 20 mV	≥90 mV
STS-1	0	<u><</u> 20 mV	≥90 mV
	1	<u><</u> 25 mV	≥115 mV

DISABLING ALOS/DLOS DETECTION:

For debugging purposes it is useful to disable the ALOS and/or DLOS detection. Setting both ALOSDIS_n and DLOSDIS_n bits disables the LOS detection on a per channel basis.

5.4.2 E3 LOS Condition:

If the level of incoming line signal drops below the threshold as described in the ITU-T G.775 standard, the LOS condition is detected. Loss of signal level is defined to be between 15 and 35 dB below the normal level. If the signal drops below 35 dB for 175 ± 75 consecutive pulse periods, LOS condition is declared. This is illustrated in Figure 19.

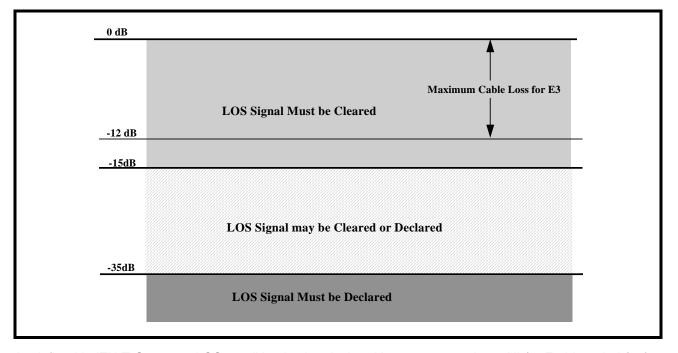


FIGURE 19. LOSS OF SIGNAL DEFINITION FOR E3 AS PER ITU-T G.775

As defined in ITU-T G.775, an LOS condition is also declared between 10 and 255 UI (or E3 bit periods) after the actual time the LOS condition has occurred. The LOS condition is cleared within 10 to 255 UI after restoration of the incoming line signal. Figure 20 shows the LOS declaration and clearance conditions.

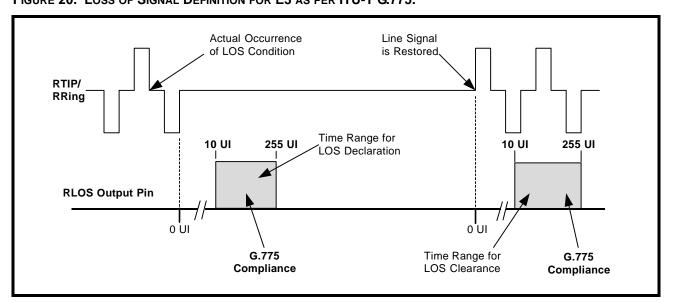


FIGURE 20. LOSS OF SIGNAL DEFINITION FOR E3 AS PER ITU-T G.775.

5.4.3 Muting the Recovered Data with LOS condition:

When the LOS condition is declared, the clock recovery circuit locks into the reference clock applied to the E3/DS3/STS1CLK pin and output this clock on the RxClk_n output. In Single Frequency Mode (SFM), the clock recovery locks into the rate clock generated and output this clock on the RxClk_n pins. The data on the RPOS_n and RNEG_n pins can be forced to zero by pulling the LOSMUT pin "High" (in Hardware Mode) or by setting the LOSMUT_n bits in the individual channel control register to "1" (in Host Mode).

NOTE: When the LOS condition is cleared, the recovered data is output on RPOS n and RNEG n pins.



6.0 JITTER:

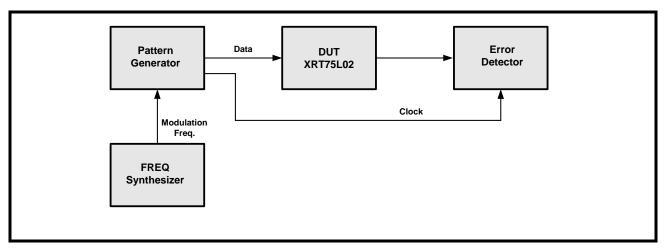
There are three fundamental parameters that describe circuit performance relative to jitter:

- Jitter Tolerance (Receiver)
- Jitter Transfer (Receiver/Transmitter)
- Jitter Generation

6.1 JITTER TOLERANCE - RECEIVER:

Jitter tolerance is a measure of how well a Clock and Data Recovery unit can successfully recover data in the presence of various forms of jitter. It is characterized by the amount of jitter required to produce a specified bit error rate. The tolerance depends on the frequency content of the jitter. Jitter Tolerance is measured as the jitter amplitude over a jitter spectrum for which the clock and data recovery unit achieves a specified bit error rate (BER). To measure the jitter tolerance as shown in Figure 21, jitter is introduced by the sinusoidal modulation of the serial data bit sequence.

FIGURE 21. JITTER TOLERANCE MEASUREMENTS



Input jitter tolerance requirements are specified in terms of compliance with jitter mask which is represented as a combination of points. Each point corresponds to a minimum amplitude of sinusoidal jitter at a given jitter frequency.

6.1.1 DS3/STS-1 Jitter Tolerance Requirements:

Bellcore GR-499 CORE, Issue 1, December 1995 specifies the minimum requirement of jitter tolerance for Category I and Category II. The jitter tolerance requirement for Category II is the most stringent. Figure 22 shows the jitter tolerance curve as per GR-499 specification.

REV. 1.0.3

- GR-253 STS-1 GR-499 Cat II 15 GR-499 Cat I JITTER AMPLITUDE (UI... 10 5 1.5 0.3 0.15 0.1 0.01 0.03 0.3 2 20 60 JITTER FREQUENCY (kHz)

FIGURE 22. INPUT JITTER TOLERANCE FOR DS3/STS-1

6.1.2 E3 Jitter Tolerance Requirements:

ITU-T G.823 standard specifies that the clock and data recovery unit must be able to accommodate and tolerate jitter up to certain specified limits. Figure 23 shows the tolerance curve.

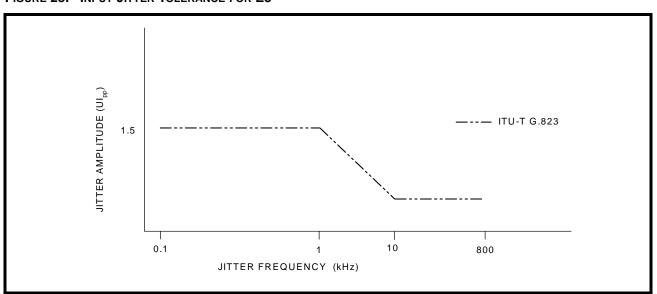


FIGURE 23. INPUT JITTER TOLERANCE FOR E3

As shown in the Figures 22 and 23 above, in the jitter tolerance measurement, the dark line indicates the minimum level of jitter that the E3/DS3/STS-1 compliant component must tolerate.

The Table 11 below shows the jitter amplitude versus the modulation frequency for various standards.



TABLE 11: JITTER AMPLITUDE VERSUS MODULATION FREQUENCY (JITTER TOLERANCE)

BIT RATE	STANDARD	INPUT JITTER AMPLITUDE (UI P-P)		MODULATION FREQUENCY					
(KB/S)	OTANDARD	A1	A2	А3	F1(Hz)	F2(Hz)	F3(KHz)	F4(KHZ)	F5(KHz)
34368	ITU-T G.823	1.5	0.15	-	100	1000	10	800	-
44736	GR-499 CORE Cat I	5	0.1	-	10	2.3k	60	300	-
44736	GR-499 CORE Cat II	10	0.3	-	10	669	22.3	300	-
51840	GR-253 CORE Cat II	15	1.5	0.15	10	30	300	2	20

6.2 JITTER TRANSFER - RECEIVER/TRANSMITTER:

Jitter Transfer function is defined as the ratio of jitter on the output relative to the jitter applied on the input versus frequency.

There are two distinct characteristics of jitter transfer: i) jitter gain (jitter peaking) defined as the highest ratio above 0dB; and ii) jitter transfer bandwidth. The overall jitter transfer bandwidth is controlled by a low bandwidth loop, typically using a voltage-controller crystal oscillator (VCXO).

The jitter transfer function is a ratio between the jitter output and jitter input for a component, or system often expressed in dB. A negative dB jitter transfer indicates the element removed jitter. A positive dB jitter transfer indicates the element had no effect on jitter.

Table 12 shows the jitter transfer characteristics and/or jitter attenuation specifications for various data rates:

TABLE 12: JITTER TRANSFER SPECIFICATION/REFERENCES

E3	DS3	STS-1
ETSI TBR-24	GR-499 CORE section 7.3.2 Category I and Category II	GR-253 CORE section 5.6.2.1

The above specifications can be met only with a jitter attenuator that supports E3/DS3/STS-1 rates.

6.3 JITTER GENERATION:

Jitter Generation is defined as the process whereby jitter appears at the output port of the digital equipment in the absence of applied input jitter. Jitter Generation is measured by sending jitter free data to the clock and data recovery circuit and measuring the amount of jitter on the output clock or the re-timed data. Since this is essentially a noise measurement, it requires a definition of bandwidth to be meaningful. The bandwidth is set according to the data rate. In general, the jitter is measured over a band of frequencies.

6.4 Jitter Attenuator:

An advanced crystal-less jitter attenuator per channel is included in the XRT75L02. The jitter attenuator requires no external crystal nor high-frequency reference clock.

In Host mode, by clearing or setting the JATx/Rx_n bits in the channel control registers selects the jitter attenuator either in the Receive or Transmit path on per channel basis. In Hardware mode, JATx/Rx pin selects globally all three channels either in Receive or Transmit path.

The FIFO size can be either 16-bit or 32-bit. In HOST mode, the bits JA0_n and JA1_n can be set to appropriate combination to select the different FIFO sizes or to disable the Jitter Attenuator on a per channel basis. In Hardware mode, appropriate setting of the pins JA0 and JA1 selects the different FIFO sizes or disables the Jitter Attenuator for all the channels. Data is clocked into the FIFO with the associated clock signal (TxClk or RxClk) and clocked out of the FIFO with the dejittered clock. When the FIFO is within two bits of



overflowing or underflowing, the FIFO limit status bit, FL_n is set to "1" in the Alarm status register. Reading this bit clears the FIFO and resets the bit into default state.

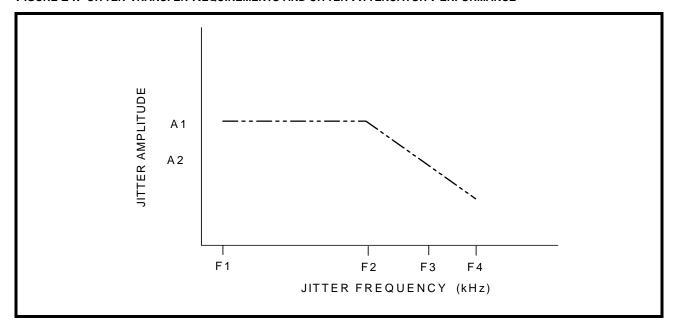
Note: It is recommended to select the 16-bit FIFO for delay-sensitive applications as well as for removing smaller amounts of jitter. Table 13 specifies the jitter transfer mask requirements for various data rates:

TABLE 13: JITTER TRANSFER PASS MASKS

RATE (KBITS)	Mask	F1 (Hz)	F2 (Hz)	F3 (Hz)	F4 (ĸHz)	A1(dB)	A2(dB)
34368	G.823 ETSI-TBR-24	100	300	3к	800K	0.5	-19.5
44736	GR-499, Cat I GR-499, Cat II GR-253 CORE	10 10 10	10k 56.6k 40	- - -	15k 300k 15k	0.1 0.1 0.1	-
51840	GR-253 CORE	10	40k	-	400k	0.1	-

The jitter attenuator in the XRT75L02 meets the latest jitter attenuation specifications and/or jitter transfer characteristics as shown in the Figure 24.

FIGURE 24. JITTER TRANSFER REQUIREMENTS AND JITTER ATTENUATOR PERFORMANCE





7.0 SERIAL HOST INTERFACE:

A serial microprocessor interface is included in the XRT75L02. The interface is generic and is designed to support the common microprocessors/microcontrollers. The XRT75L02 is configured in Host mode when the HOST/HW pin is tied "High". The serial interface includes a serial clock (SClk), serial data input (SDI), serial data output (SDO), chip select (CS) and interrupt output (INT). The serial interface timing is shown in Figure 11.

The active low interrupt output signal (INT pin) indicates alarm conditions like LOS, DMO and FL to the processor.

When configured in Host mode, the following input pins, TxLEV_n, TAOS_n, RLB_n, LLB_n, E3_n, STS-1/DS3_n, REQEN_n, JATx/Rx, JAO and JA1 are disabled and must be connected to ground.

The Table 14 below illustrates the functions of the shared pins in either Host mode or in Hardware mode.

PIN NUMBER IN HOST MODE IN HARDWARE MODE CS 29 **RxClkINV** 30 SCIk **TxClkINV** 31 SDI **RxON** 27 SDO **RxMON** 28 INT LOSMUT

TABLE 14: FUNCTIONS OF SHARED PINS

Note: While configured in Host mode, the TxON input pin will be active if the TxON_n bits in the control register are set to "1", and can be used to turn on and off the transmit output drivers. This permits a system designed for redundancy to quickly switch out a defective line card and switch-in the backup line card.

ADDRESS	PARAMETER	DATA BITS									
(HEX)	NAME	7	6	5	4	3	2	1	0		
0x00	APS/Redundancy (read/write)	Reserved		RxON-1	RxON_0	Reserved		TxON-1	TxON_0		
0x20	Interrupt Enable- Global (read/write)		Reserved						INTEN_0		
0x21	Interrupt Status (read only)		Reserved INTST_								
0x22- 0x3D	Reserved				Rese	erved		•			
0x3E	Chip_id (read only)	Device part number (7:0)									
0x3F	Chip_version (read only)			С	hip revision	number (7:	(0)				

TABLE 15: REGISTER MAP AND BIT NAMES

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TABLE 16: REGISTER MAP DESCRIPTION - GLOBAL

ADDRESS (HEX)	Түре	REGISTER NAME	SYMBOL		DESCRI	PTION	DEFAULT VALUE	
			RxON_n		On. Writing	N_1 a "1" to the bit field turns rn off the Receiver.	0	
0x00	R/W	APS/Redu ndancy	TxON_n	Bit 0 = TxON_0 Table below s based on the b	0			
				Bit	Pin	Transmitter Status		
				0	0	OFF		
				0	1	OFF		
				1	0	OFF		
				1	1	ON		
0x20	R/W	Interrupt Enable	INTEN_n	Bit 1 = INTEN_ Writing a "1" the correspond	to these bits	enable the interrupts for	0	
0x21	Read Only	Interrupt Status	INTST_n	Respective bits required. The	Bit 1 = INTST_1, Bit 0 = INTST_0. Respective bits are set to "1" if an interrupt service is required. The respective source level interrupt status registers are read to determine the cause of interrupt.			
0x22 - 0x3D			l	Rese	rved			
0x3E	Read Only	Device Number	Chip_id	This read only				
0x3F	Read Only	Version Number	Chip_version	This read only	register conta	ins chip version number		

TABLE 17: REGISTER MAP AND BIT NAMES - CHANNEL 0 REGISTERS

Address	PARAMETER	DATA BITS										
(HEX)	NAME	7	7 6 5 4				2	1	0			
0x01	Interrupt Enable (read/write)		Rese	erved		FLIE_0	RLOLIE_0	RLOSIE_ 0	DMOIE_0			
0x02	Interrupt Status (reset on read)		Rese	rved		FLIS_0	RLOLIS_0	RLOSIS_ 0	DMOIS_0			
0x03	Alarm Status (read only)	Reserved	PRBSLS_0	DLOS_0	ALOS_0	FL_0	RLOL_0	RLOS_0	DMO_0			



TABLE 17: REGISTER MAP AND BIT NAMES - CHANNEL 0 REGISTERS

ADDRESS	PARAMETER	DATA BITS									
(HEX)	NAME	7	6	5	4	3	2	1	0		
0x04	Transmit Con- trol (read/write)	Reserved		TxMON_0	INSPRBS _0	Reserved	TAOS_0	TxClkINV _0	TxLEV_0		
0x05	Receive Control (read/write)	Reserved		DLOSDIS _0	ALOSDIS _0	RxClkINV_ 0	LOSMUT_ 0	RxMON_0	REQEN_ 0		
0x06	Block Control (read/write)	Res	Reserved		RLB_0	LLB_0	E3_0	STS1/ DS3_0	SR/DR_0		
0x07	Jitter Attenuator (read/write)	Reserved		•	DFLCK_0	PNTRST_ 0	JA1_0	JATx/ Rx_0	JA0_0		
0x08	Reserved				Rese	erved			1		

TABLE 18: REGISTER MAP AND BIT NAMES - CHANNEL 1 REGISTERS

Address	PARAMETER				DATA	Вітѕ			
(HEX)	NAME	7	6	5	4	3	2	1	0
0x09	Interrupt Enable (read/write)		Rese	erved		FLIE_1	RLOLIE_1	RLOSIE_ 1	DMOIE_1
0x0A	Interrupt Status (reset on read)		Rese	erved		FLIS_1	RLOLIS_1	RLOSIS_ 1	DMOIS_1
0x0B	Alarm Status (read only)	Reserved	PRBSLS_ 1	DLOS_1	ALOS_1	FL_1	RLOL_1	RLOS_1	DMO_1
0x0C	Transmit Con- trol (read/write)	Rese	erved	TxMON_1	INSPRBS _1	Reserved	TAOS_1	TxClkINV _1	TxLEV_1
0x0D	Receive Control (read/write)	Rese	erved	DLOSDIS _1	ALOSDIS _1	RxClkINV _1	LOSMUT_ 1	RxMON_1	REQEN_1
0x0E	Block Control (read/write)	Reserved		PRBSEN_ 1	RLB_1	LLB_1	E3_1	STS1/ DS3_1	SR/DR_1
0x0F	Jitter Attenuator (read/write)	Reserved			DFLCK_1	PNTRST_ 1	JA1_1	JATx/ Rx_1	JA0_1
0x10	Reserved				Rese	erved			

TABLE 19: REGISTER MAP DESCRIPTION - CHANNEL 0

Address (Hex)	Түре	REGISTER NAME	BIT#	SYMBOL	DESCRIPTION	DEFAULT VALUE			
			D0	DMOIE_n	Writing a "1" to this bit enables an interrupt when the no transmission detected on channel output.	0			
			D1	RLOSIE_n	Writing a "1" to this bit enables an interrupt when Receive Los of Signal is detected.	0			
			D2	RLOLIE_n	Writing a "1" to this bit enables an interrupt when Receive Loss of Lock condition is detected	0			
0x01 (ch 0) 0x09 (ch 1)	R/W	Enable (source	Enable	D3	FLIE_n	Writing a "1" to this bit enables the interrupt when the FIFO Limit of the Jitter Attenuator is within 2 bits of overflow/underflow condition.	0		
	level)				NOTE: This bit field is ignored when the Jitter Attenuator is disabled.				
			D7-D4		Reserved				
			D0	DMOIS_n	This bit is set every time a DMO status change has occurred since the last cleared interrupt. This bit is cleared when the register bit is read.	0			
	(0A (ch 1) on Status		D1	RLOSIS_n	This bit is set every time a RLOS status change has occurred since the last cleared interrupt. This bit is cleared when the register bit is read.	0			
0x02 (ch 0) 0x0A (ch 1)			D2	RLOLIS_n	This bit is set every time a RLOL status change has occurred since the last cleared interrupt. This bit is cleared when the register bit is read.	0			
	rtodd	level)	D3	FLIS_n	0				
			D7-D4		Reserved				
			D0	DMO_n	This bit is set every time the MTIP_0/MRing_0 input pins have not detected any bipolar pulses for 128 consecutive bit periods.	0			
			D1	RLOS_n	This bit is set every time the receiver declares an LOS condition.	0			
			D2	RLOL_n	This bit is set every time when the receiver declares a Loss of Lock condition.	0			
			D3	FL_n	This bit is set every time the FIFO in the Jitter Attenuator is within 2 bit of underflow/overflow condition.	0			
0x03 (ch 0)	` ' '	Alarm Sta-	D4	ALOS_n	This bit is set every time the receiver declares Analog LOS condition.	0			
0x0B (ch 1)	Only	lly tus	D5	DLOS_n	This bit is set every time the receiver declares Digital LOS condition.	0			
			D6	PRBSLS_n	This bit is set every time the PRBS detector is not in sync.	0			
			D7		Reserved				



TABLE 19: REGISTER MAP DESCRIPTION - CHANNEL 0

Address (Hex)	Түре	REGISTER NAME	BIT#	SYMBOL	DESCRIPTION	DEFAULT VALUE
(11277)			D 0	T 1 5) /	Cat this hit for eahle length greater than 225	
			D0	TxLEV_n	Set this bit for cable length greater than 225 feet.	0
					NOTE: See section 4.03 for detailed description.	
			- D4	T 011 IN 11	·	
			D1	TxClkINV_ n	Set this bit to sample the data on TPOS/TNEG pins on the rising edge of TxClk.	0
			D2	TAOS_n	Set this bit to send a continuous stream of marks (All Ones) out at the TTIP and TRING pins.	0
0x04 (ch 0)	R/W	Transmit	D3		Reserved	
0x0C (ch 1)		Control	D4	INSPRBS_ n	Setting this bit causes the PRBS generator to insert a single-bit error onto the transmit PRBS data stream. Note: PRBS Generator/Detector must be enabled	0
					for this bit to have any effect.	
			D5	TxMON_n	Setting this bit causes the driver monitor its own transmit driver. When the transmit failure is detected, DMO output pin goes "High" and DMOIS bit is set. When this bit is "0", MTIP and MRing are connected to other transmit channel for monitoring.	0
			D7-D6		Reserved	
			D0	REQEN_n	Set this bit to enable the Receive Equalizer.	0
					Note: See section 5.01 for detailed description.	Ü
			D1	RxMON_n	Set this bit to configure the Receiver in monitoring mode. In this mode, the Receiver can monitor a signal at the RTIP/RRING pins that has be attenuated up to 20dB flat loss. However, internal LOS circuitry is suppressed and LOS will never assert nor LOS be declared when operating under this mode.	0
0x05 (Ch 0) 0x0D (Ch 1)	R/W	Receive Control	D2	LOSMUT_	Setting this bit causes the RPOS/RNEG outputs to "0" while the LOS condition is declared.	0
					Note: If the bit has ben set, it will remain set even after LOS condition is cleared.	
			D3	RxClkINV_	Set this bit to configure the Receiver to output RPOS/RNEG data on the falling edge of RxClk_0.	0
			D4	ALOSDIS_	Set this bit to disable the ALOS detector.	0
			D5	DLOSDIS_	Set this bit to disable the DLOS detector.	0
			D7-D6		Reserved	

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TABLE 19: REGISTER MAP DESCRIPTION - CHANNEL 0

Address (Hex)	Түре	REGISTER NAME	BIT#	SYMBOL		DESCRIPT	TION	DEFAULT VALUE	
			D0	SR/DR_n	mitter in Sing	le-Rail (NRZ) m	ne Receiver and Trans- node. etailed description.	0	
			D1	STS-1/ DS3_n	mode. Note: This				
			D2	E3_n	Setting this bi	Setting this bit configures the channel in E3 mode. Setting this bit configures the channel in Local Loop back mode.		0	
			D3	LLB_n	Setting this bi back mode.			0	
0x06 (Ch 0) 0x0E (Ch 1)	R/W	Block Con-	D4	RLB_n	Setting this bit configures the channel in Remote Loopback mode.			0	
OXOL (OII I)					RLB_n	LLB_n	Loopback Mode		
					0	0	Normal Operation		
					0	1	Analog Local		
					1	0	Remote		
					1	1	Digital		
	D5 PRBSEN_ Setting this bit enables the PRBS generator/de tor. PRBS generator generate and detect either 1 (DS3 or STS-1) or 2 ²³ -1 (for E3). The pattern generated and detected are unfra pattern.			te and detect either 2 ¹⁵ -or E3).	0				
			D7-D6			Reserve	ed		



TABLE 19: REGISTER MAP DESCRIPTION - CHANNEL 0

Address (Hex)	Түре	REGISTER NAME	BIT#	Symbol		DESCRIPTION			
			D0	JA0_n	3	g with JA1_n t shown in the ta	oit configures the Jitter able below.	0	
					JA0_n	JA1_n	Mode		
					0	0	16 bit FIFO		
					0	1	32 bit FIFO		
0x07 (Ch 0)	R/W	Jitter Attenuator			1	0	Disable Jitter Attenuator		
0x0F (Ch 1)		Alteridator			1	1	Disable Jitter Attenuator		
			D1	JATx/Rx_n	Setting this bit selects the Jitter Attenuator in the Transmit Path. A "0" selects in the Receive Path.			0	
			D2	JA1_n		g with the JA0_ shown in the ta	_n configures the Jitter able.	0	
			D3	PNTRST_n	Setting this bi the jitter atten		ad and Write pointers of	0	
			D4	DFLCK_n	Set this bit to "1" to disable fast locking of the PLL. This helps to reduce the time for the PLL to lock to incoming frequency when Jitter Attenuator switches to narrow band.			0	
			D7-D5		l	Reserve	ed		
0x08 0x10 0x18 - 0x1f			1		Reserv	ed			

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8.0 DIAGNOSTIC FEATURES:

8.1 PRBS Generator and Detector:

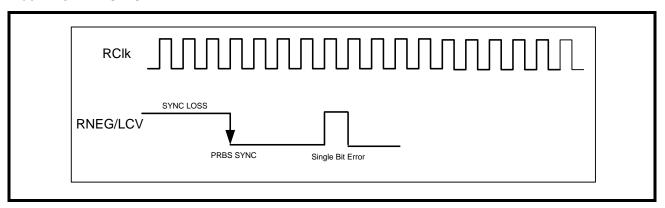
The XRT75L02 contains an on-chip Pseudo Random Binary Sequence (PRBS) generator and detector for diagnostic purpose. This feature is only available in Host mode. With the PRBSEN_n bit = "1", the transmitter will send out PRBS of 2²³-1 in E3 rate or 2¹⁵-1 in STS-1/DS3 rate. At the same time, the receiver PRBS detector is also enabled. When the correct PRBS pattern is detected by the receiver, the RNEG/LCV pin will go "Low" to indicate PRBS synchronization has been achieved. When the PRBS detector is not in sync the PRBSLS bit will be set to "1" and RNEG/LCV pin will go "High".

With the PRBS mode enabled, the user can also insert a single bit error by toggling "INSPRBS" bit. This is done by writing a "1" to INSPRBS bit. The receiver at RNEG/LCV pin will pulse "High" for one RxClk cycle for every bit error detected. Any subsequent single bit error insertion must be done by first writing a "0" to INSPRBS bit and followed by a "1".

Figure 25 shows the status of RNEG/LCV pin when the XRT75L02 is configured in PRBS mode.

NOTE: In PRBS mode, the device is forced to operate in Single-Rail Mode.

FIGURE 25. PRBS MODE



8.2 LOOPBACKS:

The XRT75L02 offers three loop back modes for diagnostic purposes. In Hardware mode, the loop back modes are selected via the RLB n and LLB n pins. In Host mode, the RLB n and LLB n bits n the Channel control registers select the loop back modes.

ANALOG LOOPBACK: 8.2.1

In this mode, the transmitter outputs (TTIP_n and TRING_n) are connected internally to the receiver inputs (RTIP_n and RRING_n) as shown in Figure 26. Data and clock are output at RCLK_n, RPOS_n and RNEG_n pins for the corresponding transceiver. Analog loop back exercises most of the functional blocks of the device including the jitter attenuator which can be selected in either the transmit or receive path.

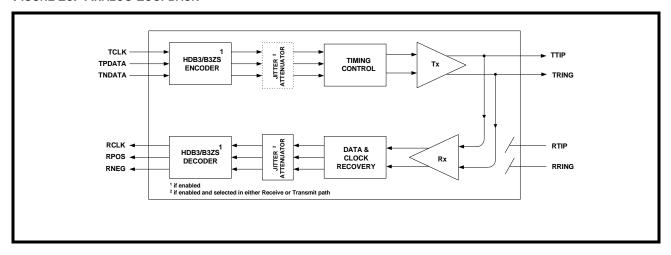
XRT75L02 can be configured in Analog Loopback either in Hardware mode via the LLB n and RLB n pins or in Host mode via LLB n and RLB n bits in the channel control registers.

Notes:

- 1. In the Analog loopback mode, data is also output via TTIP_n and TRING_n pins.
- 2. Signals on the RTIP_n and RRING_n pins are ignored during analog loop back.



FIGURE 26. ANALOG LOOPBACK

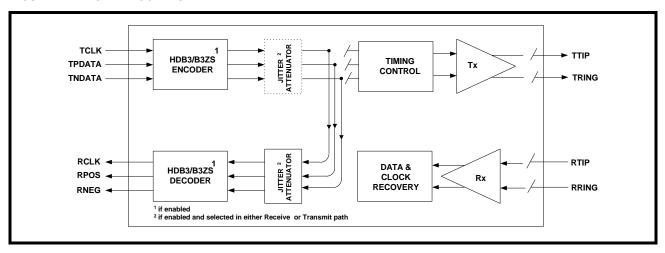


8.2.2 DIGITAL LOOPBACK:

The Digital Loopback function is available either in Hardware mode or Host mode. When the Digital Loopback is selected, the transmit clock (TxClk_n) and transmit data inputs (TPOS_n & TNEG_n) are looped back and output onto the RxClk_n, RPOS_n and RNEG_n pins as shown in Figure 27. The data presented on TxClk, TPOS and TNEG are not output on the TTIP and TRING pins. This provides the capability to configure the protection card (in redundancy applications) in Digital Loopback mode without affecting the traffic on the primary card.

Note: Signals on the RTIP_n and RRING_n pins are ignored during digital loop back.

FIGURE 27. DIGITAL LOOPBACK



8.2.3 IREMOTE LOOPBACK:

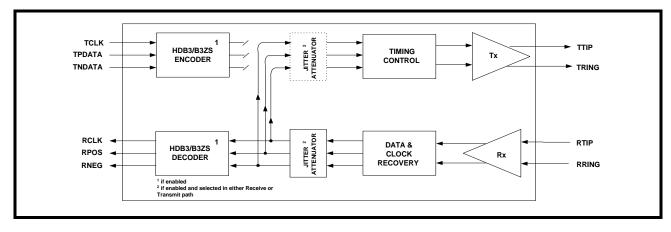
With Remote loop back activated as shown in Figure 28, the receive data on RTIP and RRING is looped back after the jitter attenuator (if selected in receive or transmit path) to the transmit path using RxClk as transmit timing. The receive data is also output via the RPOS and RNEG pins.

During the remote loop back mode, if the jitter attenuator is selected in the transmit path, the receive data after the Clock and Data Recovery Block is looped back to the transmit path and passed through the jitter attenuator using RxClk as the transmit timing.

NOTE: Input signals on TxClk, TPOS and TNEG are ignored during Remote loop back.



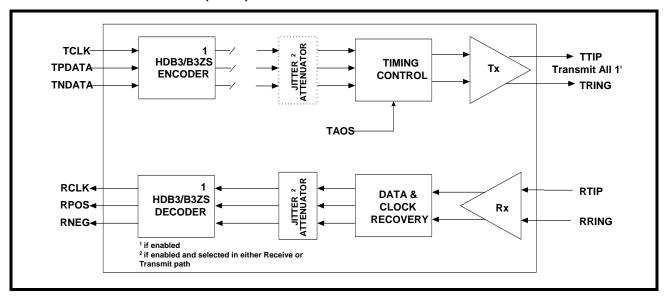
FIGURE 28. REMOTE LOOPBACK



8.3 TRANSMIT ALL ONES (TAOS):

Transmit All Ones (TAOS) can be set either in Hardware mode by pulling the TAOS_n pins "High" or in Host mode by setting the TAOS_n control bits to "1" in the Channel control registers. When the TAOS is set, the Transmit Section generates and transmits a continuous AMI all "1's" pattern on TTIP_n and TRING_n pins. The frequency of this "1's" pattern is determined by TxClk_n.TAOS data path is shown in Figure 29.

FIGURE 29. TRANSMIT ALL ONES (TAOS)



X EXAR

APPENDIX B

TABLE 20: TRANSFORMER RECOMMENDATIONS

PARAMETER	Value		
Turns Ratio	1:1		
Primary Inductance	40 μΗ		
Isolation Voltage	1500 Vrms		
Leakage Inductance	0.6 μΗ		

TABLE 21: TRANSFORMER DETAILS

PART NUMBER	Vendor	Insulation	PACKAGE TYPE
PE-68629	PULSE	3000 V	Large Thru-hole
PE-65966	PULSE	1500 V	Samll Thru-hole
PE-65967	PULSE	1500 V	SMT
T 3001	PULSE	1500 V	SMT
TG01-0406NS	HALO	1500 V	SMT
TTI 7601-SM	TransPower	1500 V	SMT

TRANSFORMER VENDOR INFORMATION

Pulse

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12220 World Trade Drive

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Tel: (858)-674-8100 FAX: (858)-674-8262

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1 & 2 Huxley Road

The Surrey Research Park Guildford, Surrey GU2 5RE

United Kingdom

Tel: 44-1483-401700 FAX: 44-1483-401701

XRT75L02 TWO CHANNEL E3/DS3/STS-1 LINE INTERFACE UNIT WITH JITTER



Asia

150 Kampong Ampat

#07-01/02

KA Centre

Singapore 368324 Tel: 65-287-8998

Website: http://www.pulseeng.com

Halo Electronics Corporate Office P.O. Box 5826

Redwood City, CA 94063

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Email: info@haloelectronics.com

Website: http://www.haloelectronics.com

Transpower Technologies, Inc.

Corporate Office

Park Center West Building

9805 Double R Blvd, Suite # 100

Reno, NV 89511

(800)500-5930 or (775)852-0140 **Email: info@trans-power.com**

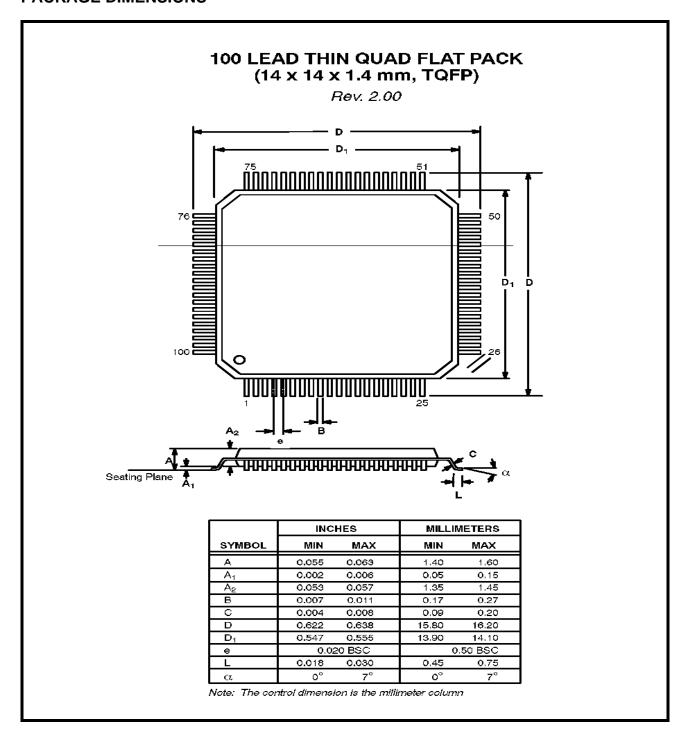
Website: http://www.trans-power.com

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ORDERING INFORMATION

PART NUMBER	PACKAGE TYPE	OPERATING TEMPERATURE RANGE		
XRT75L02IV	14x14 mm, 100 Lead Plastic QFP	-40℃ to +85℃		

PACKAGE DIMENSIONS





REVISION HISTORY

Package dimension was changed from 14 x 20 to 14 x 14.

- 1.0.1 Changed I_{CC} and P_{DD} in the electrical characteristics. Removed preliminary.
- 1.0.2 Changed description for TxON. Changed max supply V to 6.0V.
- 1.0.3 Corrected RxMON functional description; added internal LOS circuitry suppression statement.

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